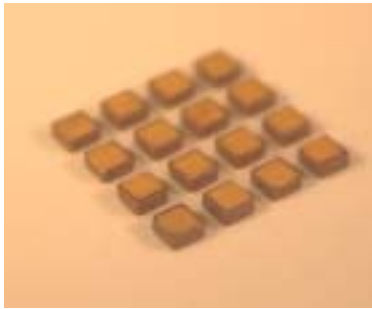


Wire-bonding Capacitors Y16, Y10 series

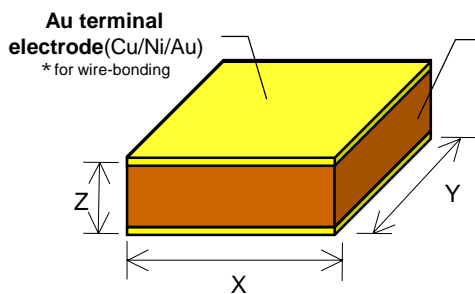
ワイヤーボンディングコンデンサ Y16, Y10シリーズ



Features

- Decoupling capacitors for IC chips.
- Applicable to be mounted inside IC packages due to their extremely thin structures.
- Available to be mounted by wire-bonding with Au plating terminals.
- available in a high temperature area up to 125 . (Temperature characteristics: X7R)

Structure / Specifications

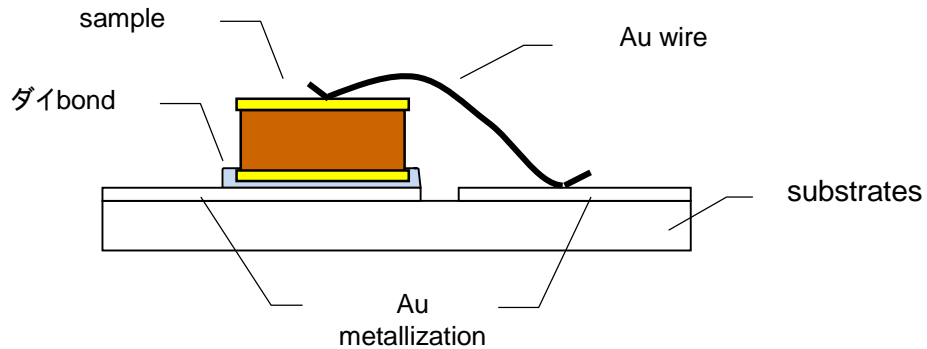


		Specifications	
Part-number		Y1606X7R1E104M	Y1006X5R1C104M
Size	X-Y	1.6 ± 0.1mm	1.0 ± 0.1mm
	Z	0.6 ± 0.1mm	0.6 ± 0.1mm
Rated voltage		25V	16Vdc
Capacitance		100nF (± 10%)	100nF (± 20%)
Temperature characteristics	Characteristics	X7R [± 15%]	X5R [± 15%]
	Temperature	-55 ~ 125	-55 ~ 85

Capacitance and size are customized. Please feel free to ask further information.

Application example

*** Applicable to be mounted inside IC packages due to their extremely thin structures.**



Characteristics evaluation sample : Y1606X7R1E104M

